

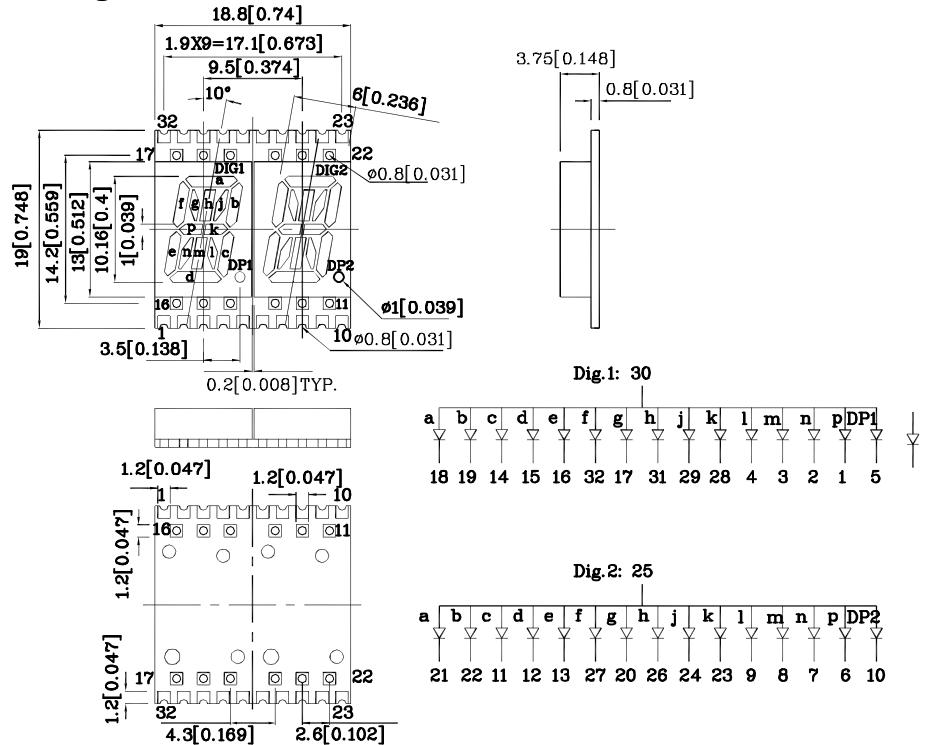
Features

- 0.4 inch digit height
- Robust package
- Low power consumption
- Standard configuration: Gray face w/ white segments
- Standard Package: 250pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS Compliant



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Package Schematics



Notes:

1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01") unless otherwise noted.
2. Specifications are subject to change without notice.
3. The gap between the reflector and PCB shall not exceed 0.25mm.

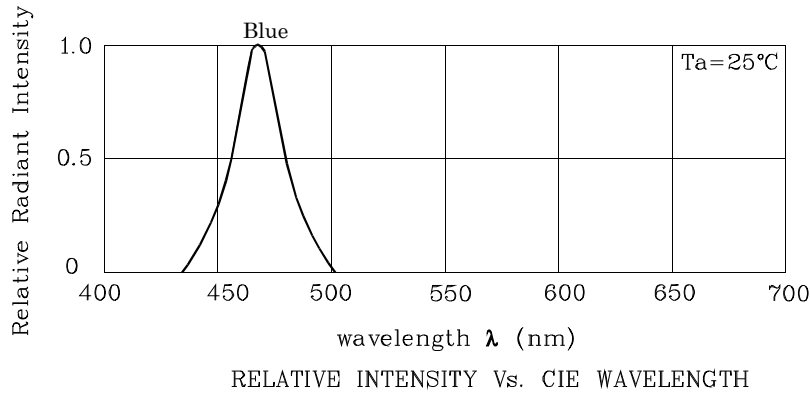
Absolute Maximum Ratings (T _A =25°C)		Blue (InGaN)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	100	mA
Power Dissipation	P _D	120	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

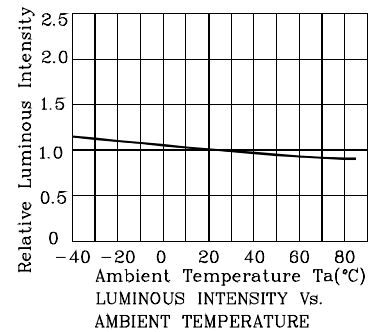
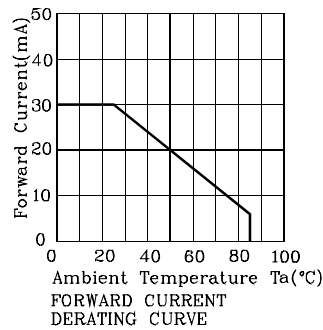
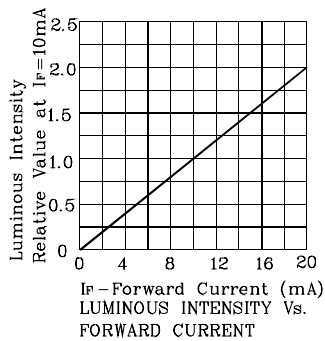
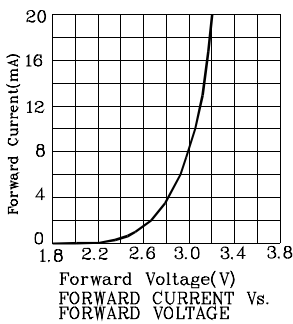
Operating Characteristics (T _A =25°C)		Blue (InGaN)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	3.05	V
Forward Voltage (Max.) (I _F =10mA)	V _F	4	V
Reverse Current (Max.) (V _R =5V)	I _R	10	µA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λ _P	468*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λ _D	465*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	21	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	100	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I _F =10mA) ucd		Wavelength CIE127-2007* nm λ _P	Description
			min.	typ.		
XZFABBA10A2	Blue	InGaN	2200*	5790*	468*	Common Anode, Rt.Hand Decimal.

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ Blue



LED is recommended for reflow soldering and soldering profile is shown below.

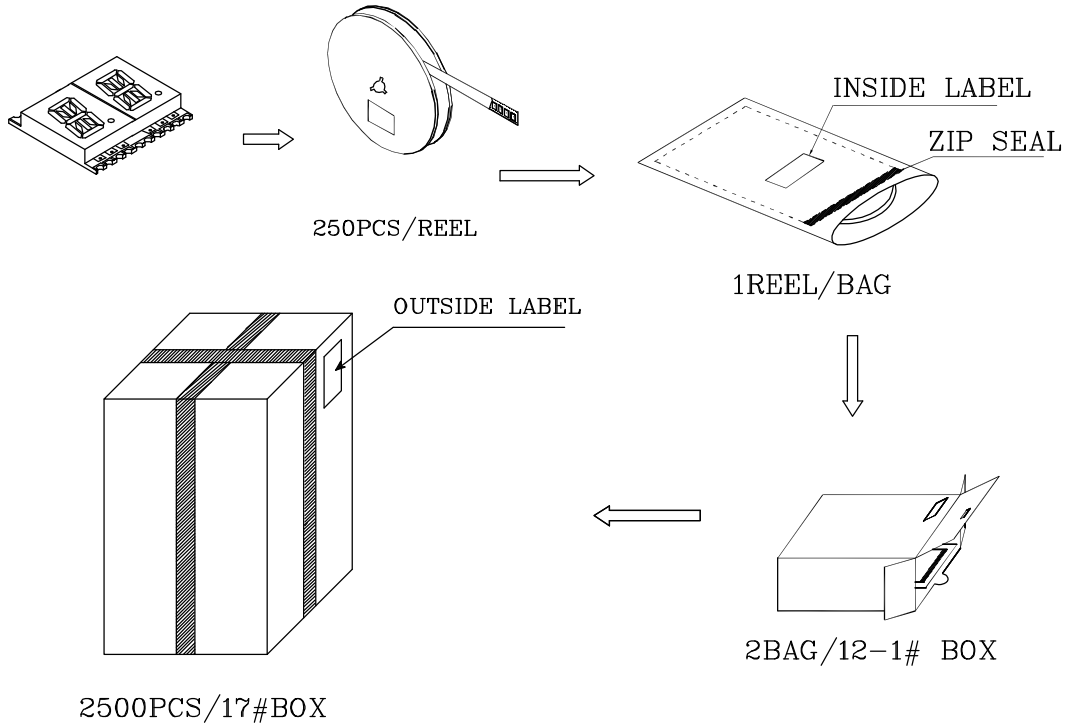
Reflow Soldering Profile for SMD Products (Pb-Free Components)



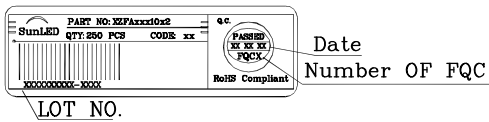
Notes:

1. Maximum soldering temperature should not exceed 260°C
2. Recommended reflow temperature: 145°C~260°C
3. Do not put stress to the epoxy resin during high temperatures conditions

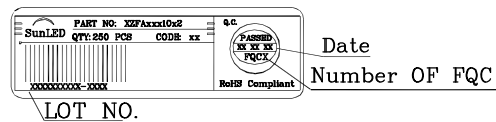
PACKING & LABEL SPECIFICATIONS



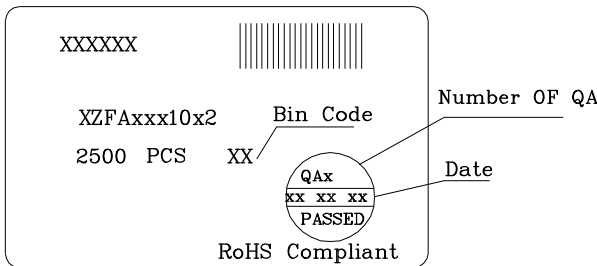
Inside LABEL On Tape



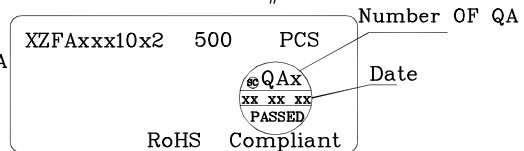
Outside LABEL On BAG



Outside LABEL On 19#Box



Outside LABEL On 12#Box



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2. Contents within this document are subject to improvement and enhancement changes without notice.
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6. Additional technical notes are available at <http://www.SunLEDusa.com/TechnicalNotes.asp>